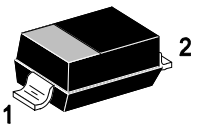
LMSZ5245BT1G
S-LMSZ5245BT1G

Zener Voltage Regulators
500 mW SOD-123 Surface Mount



SOD123

1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- 500 mW Rating on FR−4 or FR−5 Board
- Package designed for optimal automated board assembly
- Small package size for high density applications
- General purpose, medium current
- ESD rating of Class 3 (>16 kV) per Human Body Model

2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LMSZ5245BT1G	H5	3000/Tape&Reel
LMSZ5245BT3G	H5	10000/Tape&Reel

3. THERMAL CHARACTERISTICS

Parameter	Symbol	Limits	Unit
Total Device Dissipation, FR−5 Board (Note 1) @ TL = 75ºC Derate above 75ºC	PD	 500 6.7	 mW mW/ºC
Thermal Resistance, Junction–to–Ambient(Note 2)	RΘJA	340	ºC/W
Thermal Resistance, Junction–to–Lead(Note 2)	RΘJL	150	ºC/W
Junction and Storage temperature	TJ,Tstg	−55～+150	°C

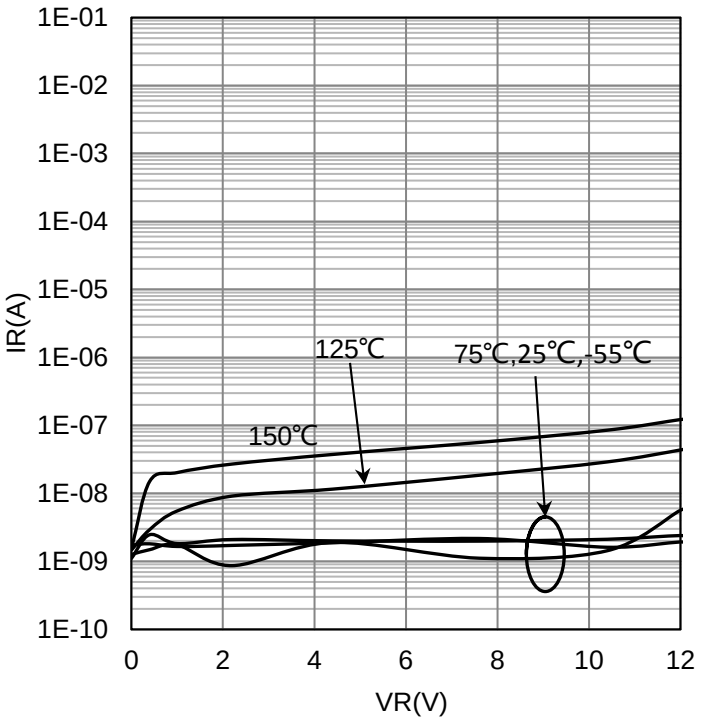
1. FR−5 = 3.5 X 1.5 inches, using the minimum recommended footprint.
2. Thermal Resistance measurement obtained via infrared Scan Method.

4. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

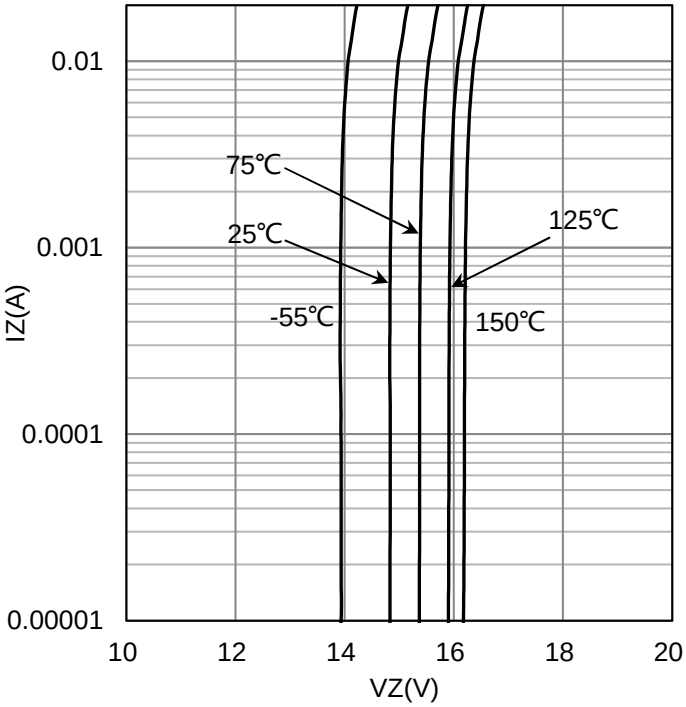
Characteristic	Symbol	Min.	Typ.	Max.	Unit
Zener voltage(Note 3 and 4） (IZT=8.5mA)	VZ	14.25	15	15.75	V
Operating resistance(Note 5) (IZT=8.5mA)	ZZT	-	-	16	Ω
Rising operating resistance(Note 5) (IZK=0.25mA)	ZZK	-	-	600	Ω
Reverse Leakage Current (VR=11V)	IR	-	-	0.1	μA

3. The type numbers shown have a standard tolerance of ±5% on the nominal Zener voltage.
4. Nominal Zener voltage is measured with the device junction in thermal equilibrium at TL = 30°C±1°C.
5. ZZT and ZZK are measured by dividing the AC voltage drop across the device by the ac current applied. The specified limits are for IZ(AC) = 0.1 IZ(dc) with the AC frequency = 1 KHz.

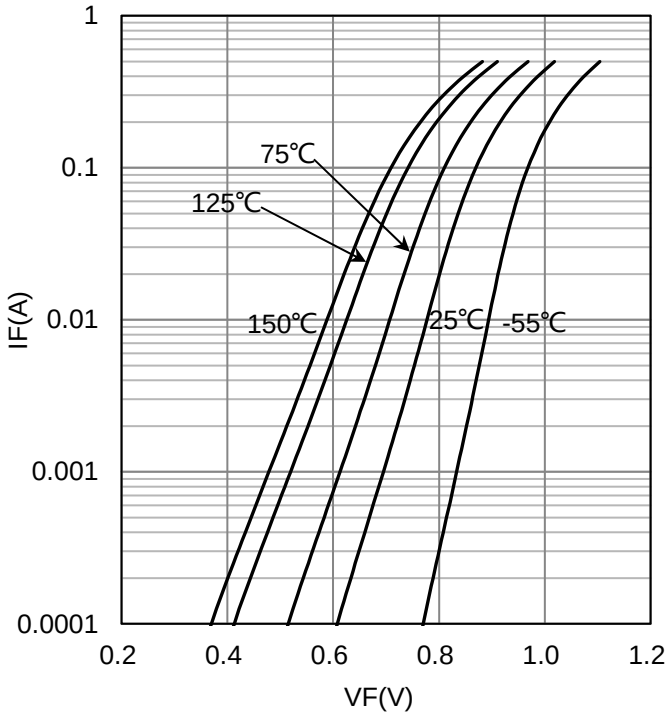
5. ELECTRICAL CHARACTERISTICS CURVES



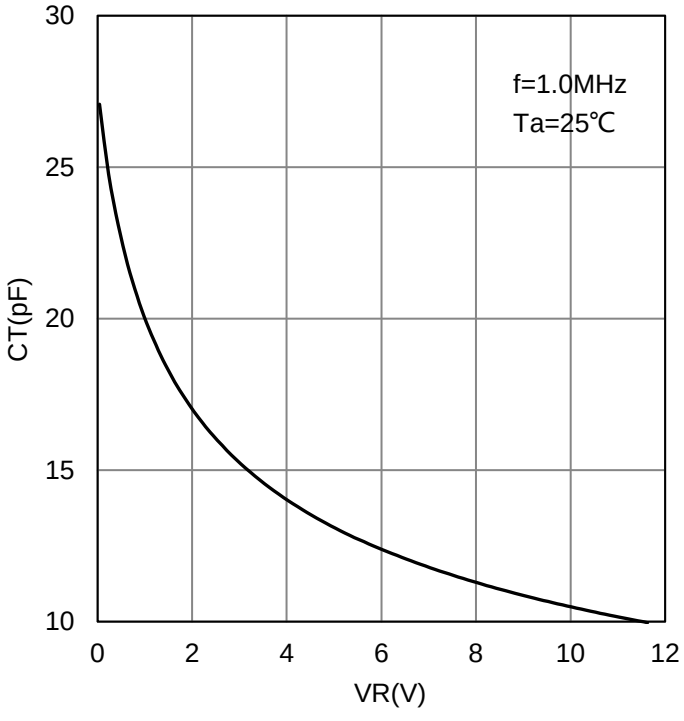
IR vs. VR



IZ vs.VZ

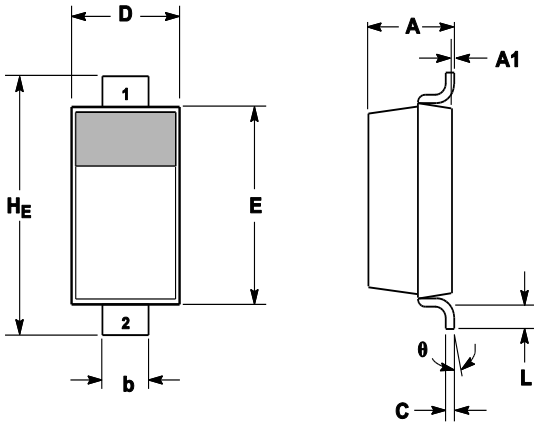


IF vs.VF



CT vs.VR

6.OUTLINE AND DIMENSIONS

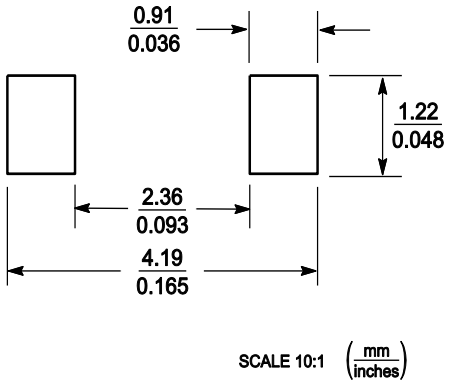


Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.94	1.17	1.35	0.037	0.046	0.053
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.51	0.61	0.71	0.020	0.024	0.028
c	---	---	0.15	---	---	0.006
D	1.40	1.60	1.80	0.055	0.063	0.071
E	2.54	2.69	2.84	0.100	0.106	0.112
H_E	3.56	3.68	3.86	0.140	0.145	0.152
L	0.25	---	---	0.010	---	---
θ	0°	---	10°	0°	---	10°

7.SOLDERING FOOTPRINT



DISCLAIMER

- Curve guarantee in the specification. The curve of test items with electric parameter is used as quality guarantee. The curve of test items without electric parameter is used as reference only.

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